

## PARA LIGHT ELECTRONICS CO., LTD.

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# DATA SHEET

PART NO.: C403I-12

REV: A/1

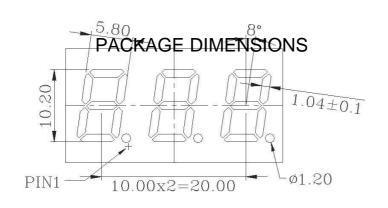
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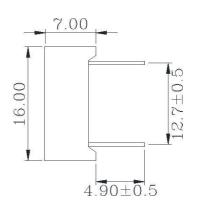
LD-R/RD012

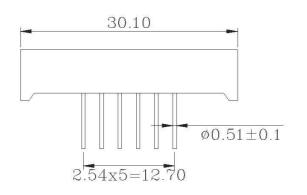


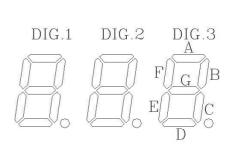
## C403I-12 REV:A / 1

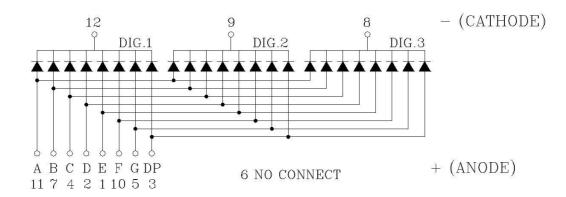
#### 0.40 INCH THREE DIGITS DISPLAY











NOTES: 1. All dimensions are in millimeters. (inches)

- 2. Tolerance is  $\pm$  0.25(0.010") unless otherwise specified.
- 3. Pls. contact with us when your production need to be operated under the Pb free process.



## C403I-12

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#### 0.40 INCH THREE DIGITS DISPLAY

#### **FEATURES**

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10.00mm (0.4 inch ) DIGIT HEIGHT COMMON CATHODE I.C. COMPATIBLE LOW POWER CONSUMPTIONP Pb FREE PRODUCTS BLACK FACE, WHITE SEGMENTS

Raw Ma	terial : GaAlAs/GaAs		
ABSOLL	TE MAXIMUM RATING : ( Ta = 25°C )		
SYMBOL	PARAMETER	RED	UNIT
PD	Power Dissipation Per Segment	60	m₩
VR	Reverse Voltage Per Segment	5	V
IAF	Continuous Forward Current Per Segment	30	mA
IPF	Peak Forward Current Per Segment (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
	Derating Linear From 25°C Per Segment	0.4	—mA/°C

Topr	Operating Temperature Range		_35°C to 85°C			
Tstg	Storage Temperature Range			_35°	C to 85	°C
ELECTI	RO-OPTICAL CHARACTERI	STICS : ( Ta = 25°	C)			
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage , Per Segment	IF = 20mA		1.8	2.2	V
IR	Reverse Current , Per Segment	VR = 5V			100	μA
λР	Peak Emission Wavelength	IF = 20mA		660		nm
λD	Dominant Wavelength	IF = 20mA		643		nm
Δλ	Spectral Line Half—Width	IF = 20mA		20		nm

2.4

6.0

mcd

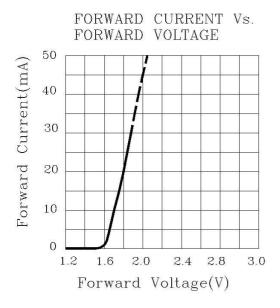
Luminous Intensity Per Segment IF = 10mA

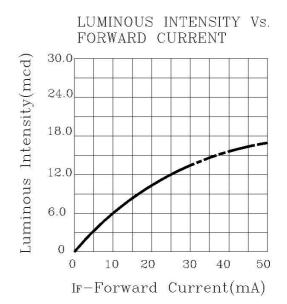
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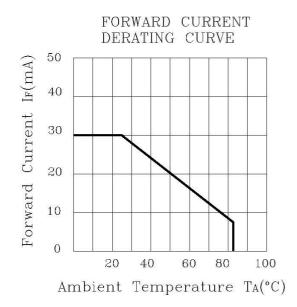


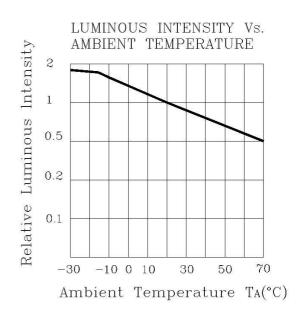
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## 0.40 INCH THREE DIGITS DISPLAY









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#### DIGITS 0.40 INCH DISPLAY THREE

SOLDERING		
METHOD	SOLDERING CONDITIONS	REMARK
		Solder no closer than 2mm from
DIP	Bath temperature: 260 max	the base of the package
SOLDERING	Immersion time: within 5 sec	Using soldering flux," RESIN FLUX"
		is recommended.
		During soldering, take care not to
SOLDERING	Soldering iron: 30W or smaller	press the tip of iron against the
IRON	Temperature at tip of iron: 260 or lower	PIN.
IIXON	Soldering time: within 5 sec.	(To prevent heat from being

transferred directly to the PIN.)

1) When soldering the PIN of Display in a jig that the package is fixed with a panel (See flg.1), be careful not to stress the PIN with iron tip. When soldering Display in a condition that the package is fixed with a panel, be careful not to ding and stress the surface of Display on the panel to avoid damaging the Display.

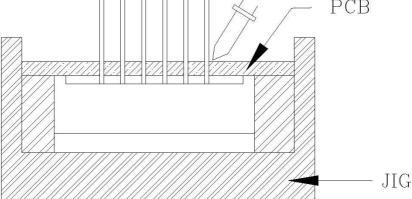


Fig.1

Regarding solution in the tinning oven for product-tinning, compound sub-solution made of tin & copper and silver is proposed with the temperature of Celsius 260. The proportion of the alloyed solution is tin 95.5: copper 3.5: silver 0.5 by percentage. The time of tinning is constantly 3 seconds.

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